

Claims

- [c1] 1. A chip structure, at least comprising:
a chip, having at least a bonding pad and a transmission line on a chip surface, wherein the transmission line is coupled to the bonding pad; and
a passivation layer, covering the chip surface, wherein the passivation has an opening to expose the bonding pad, wherein a cross-section of the opening includes a straight line and an arc connecting to two ends of the straight line, and the straight line is near to a connection terminal between the transmission line and the bonding pad.
- [c2] 2. The chip structure of claim 1, wherein a length of the straight line is less than or equal to a radius of the arc.
- [c3] 3. The chip structure of claim 1, wherein a length of the straight line is between a radius of the arc and a diameter of the arc.
- [c4] 4. The chip structure of claim 1, wherein the passivation layer includes an organic passivation layer.
- [c5] 5. The chip structure of claim 1, wherein the passivation layer includes an inorganic passivation layer.

- [c6] 6. A chip structure, at least comprising:
a chip, having at least a bonding pad and a transmission line coupled to the bonding pad, wherein the bonding pad and the transmission line are on a chip surface; and
a passivation layer, covering the chip surface, wherein the passivation has an opening to expose the bonding pad, wherein a cross section of the opening includes a curving line and an arc connecting to two ends of the curving line, wherein the curving line is concave to the arc and near to a connection terminal between the transmission line and the bonding pad.
- [c7] 7. The chip structure of claim 6, wherein each point of the curving line has a substantially equal distance to the connection terminal between the transmission line and the bonding pad.
- [c8] 8. The chip structure of claim 6, wherein a curvature of the curving line is less than or equal to a curvature of the arc.
- [c9] 9. The chip structure of claim 6, wherein a curvature of the curving line is greater than or equal to a curvature of the arc.
- [c10] 10. The chip structure of claim 6, wherein the passivation layer includes an organic passivation layer.

[c11] 11. The chip structure of claim 6, wherein the passivation layer includes an inorganic passivation layer.